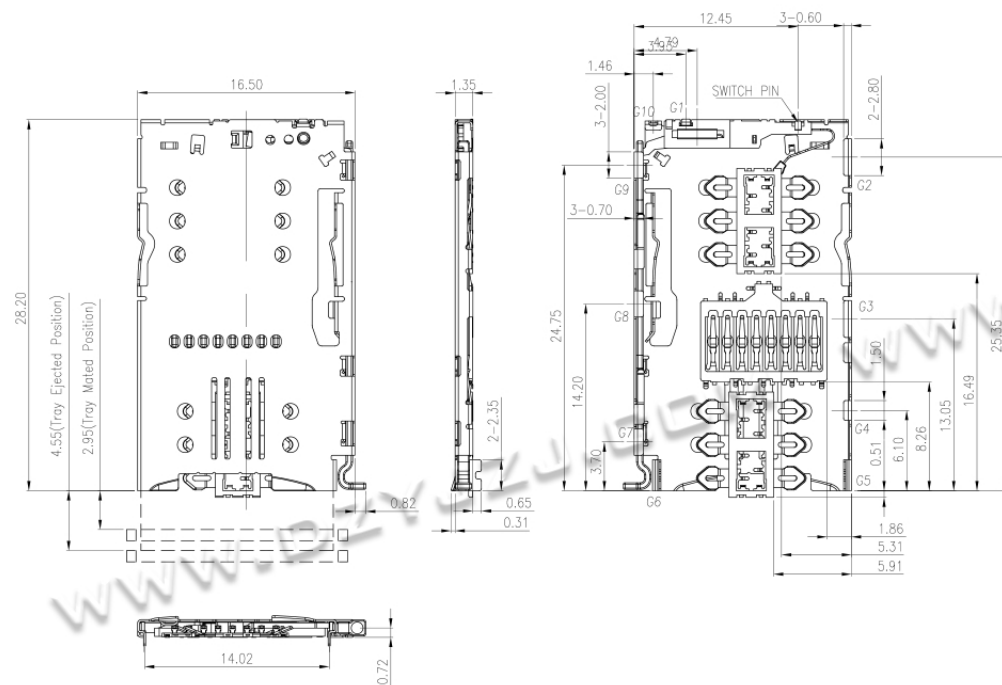


NOTES:

1. MATERIAL:

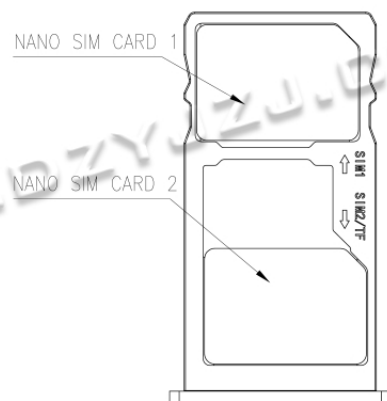
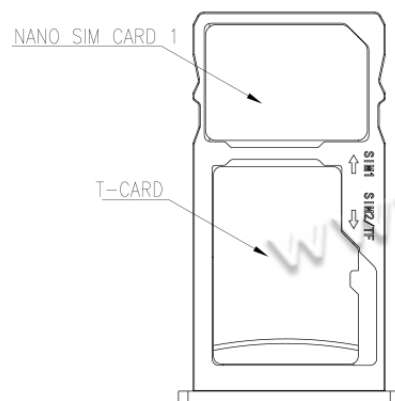
- 1.1 HOUSING:THERMOPLASTIC,UL 94V-0;COLOR:BLACK
- 1.2 CONTACT:COPPER ALLOY
- 1.3 CRANK:STAINLESS STEEL T=0.4mm
- 1.4 ROD:STAINLESS STEEL T=0.5mm
- 1.5 SHELL:STAINLESS STEEL T=0.15mm
- 1.6 SWITCH BLOCK:THERMOPLASTIC,UL 94V-0;
30% G/F FILLED;COLOR:BLACK
- 1.7 SWITCH PIN:STAINLESS STEEL T=0.15mm

2. FINISH:

- 2.1 CONTACT: GOLD PLATING ON CONTACT AREA(SEE P/N) 1u"Au
PLATING ON SOLDER TAILS
50u" MIN. NICKEL UNDERPLATING OVER ALL
- 2.2 SHELL: 1u" MIN GOLD PLATING ON SOLDER TAILS, 50u"
NICKEL UNDERPLATED.

3. SPECIALITY:

- 3.1 VOLTAGE RATING:50V
- 3.2 WITHSTANDING VOLTAGE:AC250V R.M.S
- 3.3 CURRENT RATING:1.0A
- 3.4 INSULATION RESISTANCE:1000MEG.OHM MIN AT DC 250V
- 3.5 CONTACT RESISTANCE:100 MILL.OHM MAX
- 3.6 OPERATION TEMPERATURE: -20°C~+85°C
- 3.7 DURABILITY:1000 CYCLES



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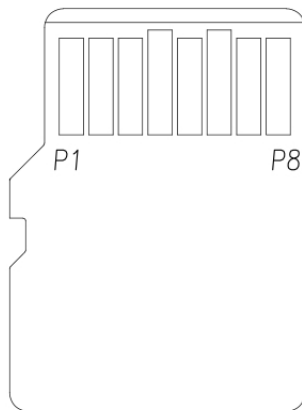
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 1.35H 分体式 三选二 组合式卡座
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC58-31N128-135
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2012071207
			SHEET NO. 1 OF 1



- NOTES:
1. MATERIAL:
 - 1.1 HOUSING:THERMOPLASTIC UL94V-0; COLOR BLACK.
 - 1.2 CONTACT TERMINAL:COPPER ALLOY.
 2. FINISH:
 - 2.1 CONTACT:AU PLATING ON CONTACT AREA(SEE P/N DESCRIPTION)
50U" MIN NICKEL UNDER PLATING OVER ALL
1U" MIN AU PLATING ON SOLDER AREA
 3. SPECIALTY:
 - 3.1 VOLTAGE RATING:50V
 - 3.2 WITHSTANDING VOLTAGE:AC250V R.M.S
 - 3.3 CURRENT RATING:0.5A
 - 3.4 INSULATION RESISTANCE:1000MEG.OHM MIN AT DC 250V
 - 3.5 CONTACT RESISTANCE:100 MILL.OHM MAX
 - 3.6 OPERATION TEMPERATURE: -20°C~+85°C
 - 3.7 DURABILITY:3000 CYCLES

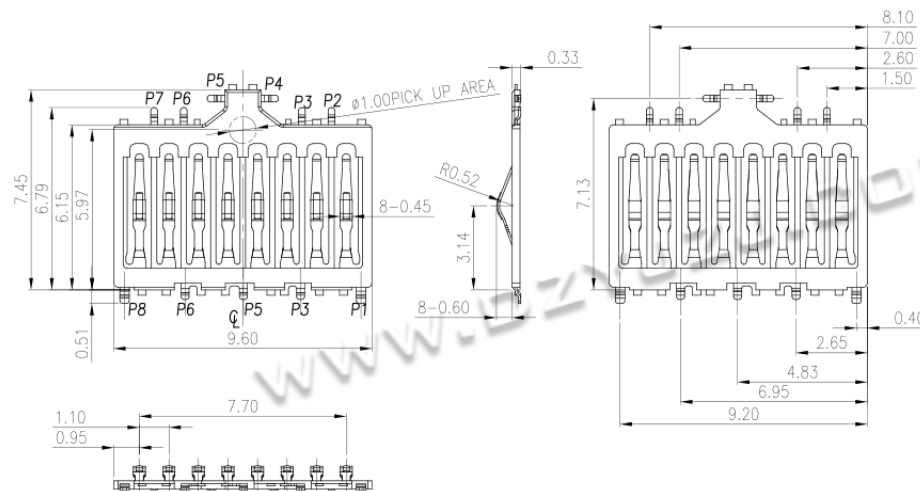
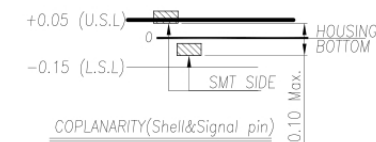
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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X.* $\pm 2'$ X.* $\pm 0.5'$		DRAWN BY : 陈一鸣		DATE : 2014-02-23		PART NAME: 1.35H 三选二分体式SIM卡	
 UNIT: mm [inch]		CHECKED BY: 马跃		DATE : 2014-02-23		PART NO.	HYC58-3IN128-135-S
		APPROVED BY: 邱敏		DATE : 2014-02-23		MOLD NO.	
						DRAW NO:	HYC-2012071207
SCALE:1:1 SIZE: A4				SHEET NO.		1 OF 1	



Micro-SD CARD

Memory Card Pin Assianment			
Pin No.	NAME	TYPE	DESCRIPTION
1	DAT 2	I/O/PP	Date Line(bit2)
2	CD/DAT 3	I/O/PP	Card Detect/Date Line(bit3)
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Colck
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Date Line(bit0)
8	DAT1	I/O/PP	Date Line(bit1)



NOTES:

1. MATERIAL:

1.1 HOUSING:THERMOPLASTIC,UL 94V-0;COLOR:BLACK

1.2 CONTACT TERMINAL:COPPER ALLOY

2. FINISH:

2.1 CONTACT: Au PLATING ON CONTACT AREA (SEE P/N DESCRIPTION)

50u" MIN NICKEL UNDERPLATING OVER ALL

1u" MIN Au PLATING ON SOLD AREA,

3. SPECIALITY:

3.1 VOLTAGE RATING:50V

3.2 WITHSTANDING VOLTAGE:AC250V R.M.S

3.3 CURRENT RATING:0.5A

3.4 INSULATION RESISTANCE:1000MEG.OHM MIN AT DC 250V

3.5 CONTACT RESISTANCE:100 MILL.OHM MAX

3.6 OPERATION TEMPERATURE: -20°C~+85°C

3.7 DURABILITY:3000 CYCLES



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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X.' ±2" X.X' ±0.5'



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

1.35H 三选二分体式T卡

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC58-31N128-135-T

APPROVED BY:

邱敏

DATE :

2014-02-23

MOLD NO.

DRAW NO:

HYC-2012071207

SHEET NO.

1 OF 1